

Customer No.: 31561  
Application No.: 10/605,163  
Docket No.: 10230-US-PA

**AMENDMENTS**

**In the Title:**

Please amend the previously presented title of the invention: "MULTI-CHIP MODULE PACKAGE" to "SEMICONDUCTOR PACKAGE WITH A HEAT SPREADER".

Customer No.: 31561  
Application No.: 10/605,163  
Docket No.: 10230-US-PA

**In the Specification:**

Please amend paragraph [0030] as follows:

[0030] The heat spreader 270 is disposed on the active surface 232 of the chip 230 and disposed in the opening 214 of the substrate 210, and is bonded to the chip 230 through the bumps 284, each of which connects a contact 238 of the chip 230 and the heat spreader 270. The heat spreader 270 also can be a chip without electronic functions, dummy chip, which comprises a material such as silicon, and the bumps 284 have no signal transmission function. Moreover, the heat spreader 270 can be plated with gold 272 to improve the adhesion between the heat spreader 270 and the chip 230, and to improve the adhesion between the heat spreader 270 and the motherboard 300 (FIG. 3). In addition, the heat spreader also can be electrically connected to the ground contacts (not shown) of the chip 230 through ground bump, which is one of the bumps 284.